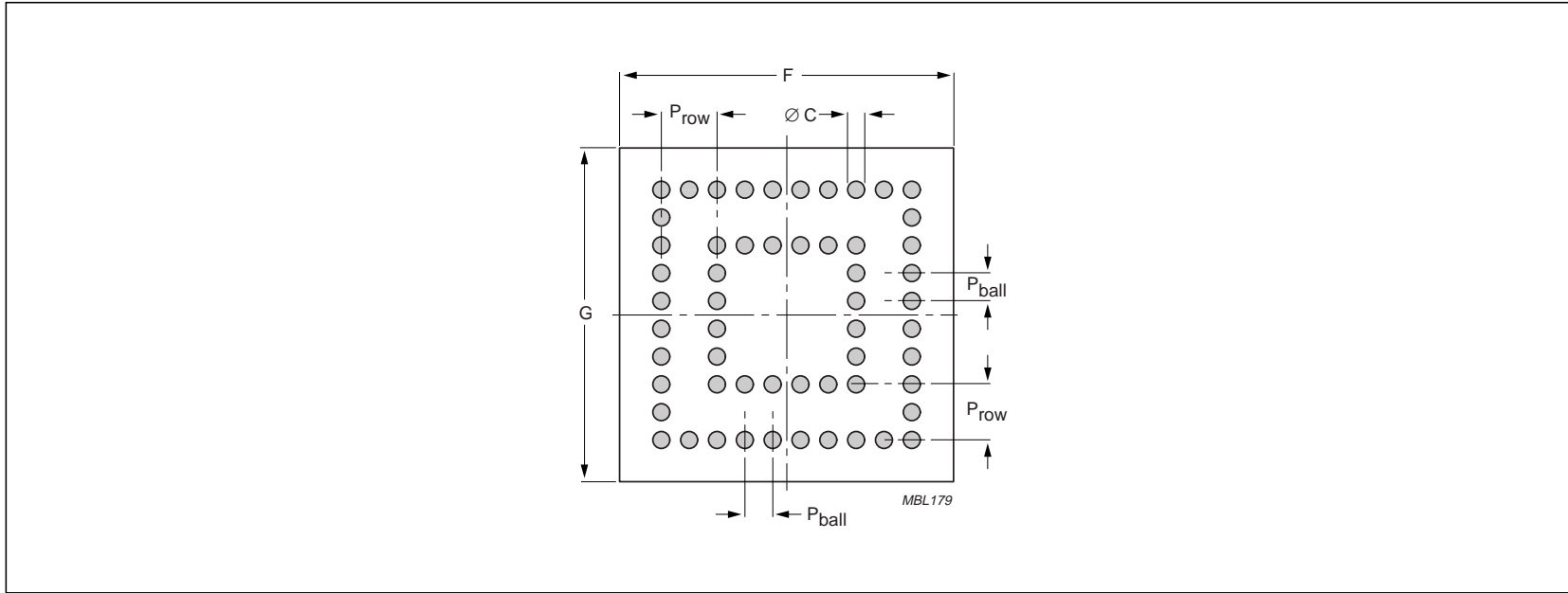


BGA, HBGA, LFBGA & TFBGA FOOTPRINT (REFLOW SOLDERING)



Reflow soldering⁽¹⁾

PACKAGE NAME	PHILIPS OUTLINE CODE	FOOTPRINT DIMENSIONS (mm)						PLACEMENT ACCURACY
		P _{ball}	P _{row}	P _{ball dia}	C	F	G	
BGA156	SOT472-1	1.00	1.00	0.50	0.45	15.30	15.30	±0.10
BGA256	SOT466-1	1.27	1.27	0.75	0.60	27.30	27.30	±0.10
BGA256	SOT471-1	1.27	1.27	0.50	0.60	27.30	27.30	±0.10
BGA292	SOT489-1	1.27	1.27	0.75	0.60	27.30	27.30	±0.10
BGA316	SOT531-1	1.27	1.27	0.75	0.60	27.30	27.30	±0.10
BGA388	SOT532-1	1.27	1.27	0.75	0.60	35.50	35.50	±0.10
BGA492	SOT514-1	1.27	1.27	0.75	0.60	35.40	35.40	±0.10
HBGA292	SOT553-1	1.27	1.27	0.75	0.60	27.30	27.30	±0.10
LFBGA40	SOT515-1	0.50	1.00	0.30	0.255	5.20	5.20	±0.10
LFBGA48	SOT488-1	0.50	1.00	0.30	0.255	5.75	5.75	±0.10
LFBGA56	SOT516-1	0.50	1.00	0.30	0.255	6.20	6.20	±0.10
LFBGA64	SOT534-1	0.80	0.80	0.46	0.425	8.30	8.30	±0.10

LFBGA84	SOT518-1	0.50	1.00	0.30	0.255	7.20	7.20	±0.10
LFBGA96	SOT536-1	0.80	0.80	0.46	0.425	5.80	13.80	±0.10
LFBGA114	SOT537-1	0.80	0.80	0.46	0.425	5.80	16.30	±0.10
LFBGA144	SOT512-1	0.80	0.80	0.40	0.425	10.30	10.30	±0.10
TFBGA56	SOT542-1	0.50	1.00	0.32	0.275	6.20	6.20	±0.10
TFBGA64	SOT543-1	0.50	0.50	0.32	0.275	6.20	6.20	±0.10

Note

1. The BGA family of packages are not suitable for wave soldering.